ULTRA-LOW PROFILE MICRO ARRAYS

**SPECIFICATIONS**
For complete specifications and recommended PCB layouts see www.samtec.com/ZA8

Insulator Material: FR4
Contact Material: BeCu
Plating: Au over 50 µ" (1.27 µm) Ni
Current Rating: .8 A per pin (10 pins powered)
Operating Temp Range: -55 °C to +105 °C
RoHS Compliant: Yes

Note: Solder ball parts will come with a pick & place pad.

**APPLICATION**
Dual compression or single compression with solder balls

**DESIGN FLEXIBILITY**
The Z-Ray® platform is highly-customizable:

<table>
<thead>
<tr>
<th>PITCH</th>
<th>STACK HEIGHT</th>
<th>DENSITY</th>
<th>RUGGEDIZING</th>
<th>CONSTRUCTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>≥ 0.65 mm</td>
<td>0.50 mm to 4.00 mm</td>
<td>Up to 1,200 contacts/square inch</td>
<td>Latches, Thermal Spreaders, Quick-release Spring Constraints</td>
<td>Multi-layer FR4 (e.g., Pitch Spreaders)</td>
</tr>
</tbody>
</table>

Note: Some lengths, styles and options are non-standard, non-returnable.

**SOLDER**

<table>
<thead>
<tr>
<th>TERMINATION</th>
<th>HEIGHT</th>
<th>PLATING</th>
<th>ROWS</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 = Single Compression with Solder Balls (-10 &amp; -20 positions only)</td>
<td>-1.00 = (1.00 mm) .040&quot; Height</td>
<td>-Z = 6 µ&quot; (0.15 µm) Gold in contact area</td>
<td>-10 = Ten Rows</td>
</tr>
<tr>
<td>2 = Dual Compression (-16, -28, -30 &amp; -40 positions only)</td>
<td></td>
<td></td>
<td></td>
</tr>
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</table>

**HIGH-SPEED CHANNEL PERFORMANCE**

1 mm Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

14 Gbps

**POSITIONS PER ROW**

<table>
<thead>
<tr>
<th>ZA8</th>
<th>-10, -20, -30, -40</th>
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</thead>
</table>

**TERMINATION**

<table>
<thead>
<tr>
<th>10 x 10 COMPRESSION WITH SOLDER BALLS</th>
</tr>
</thead>
<tbody>
<tr>
<td>20 X 10 COMPRESSION WITH SOLDER BALLS</td>
</tr>
</tbody>
</table>

**30 g normal force with (0.20 mm) .008" contact deflection**

**Dual compression or single compression with solder balls**

**Solder ball option**

(1.00 mm) .040" height

Due to technical progress, all designs, specifications and components are subject to change without notice.

www.samtec.com

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.